

20V N-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

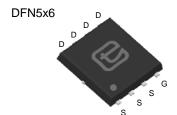
 V_{DS} 20V I_{D} (at V_{GS} =10V) 120A

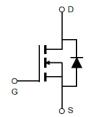
 $R_{DS(ON)}$ (at $V_{GS} = 10V$) $< 3.4m\Omega$ $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) $< 3.8m\Omega$

 $R_{DS(ON)}$ (at V_{GS} =2.5V) < 5.1m Ω

100% UIS Tested







Part Number Package Type		Form	Marking	
TTG120N02GT	DFN5x6	Tape&Reel	120N02GT	

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	±20	V	
Ocation of David Comment B	T _C =25°C		51	А	
Continuous Drain Current B	T _C =100°C	I _D	51		
Pulsed Drain Current A		I _{DM}	360	A	
Avalanche Current ^A		I _{AS}	26	А	
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	101	mJ	
Dawer Dissipation C	T _C =25°C	Б	108	W	
Power Dissipation ^C	T _C =100°C	ŀ P _D	54.3	W	
Junction and Storage Temperate	ure Range	T _J , T _{STG}	-55 to 175	°C	

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	1.38	0000	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W	



Symbol	Parameter	Conditions		Value			Units	
Symbol	Parameter	Conditions			Тур	Max	Units	
STATIC P	ARAMETERS							
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		20			V	
I _{DSS}		V _{DS} =20V, V _{GS} =0V	T _J =25°C			1		
	Zero Gate Voltage Drain Current		T _J =100°C			25	μA	
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$				±100	nA	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		0.5	0.7	1.2	V	
		V _{GS} =10V, I _D =30A		2.6	3.4	mΩ		
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =30A		2.9	3.8	mΩ		
		V _{GS} =2.5V, I _D =30A		3.9	5.1	mΩ		
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =20A		15		S		
V_{SD}	Diode Forward Voltage	I _S =50A, V _{GS} =0V				1	V	
I _s	Maximum Body-Diode Continuous Current B					51	Α	
DYNAMIC	PARAMETERS				-			
C _{iss}	Input Capacitance				4066			
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 10V, f = 1MH_Z$			1107		pF	
C _{rss}	Reverse Transfer Capacitance				655			
SWITCHIN	IG PARAMETERS							
Q _g (10V)	Total Gate Charge				118			
Q_{gs}	Gate Source Charge	$V_{GS} = 10V, V_{DS} = 10V,$	I _D =50A		7		nC	
Q_{gd}	Gate Drain Charge]			22			
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 10V, I_{D} = 50A,$ $R_{G} = 3\Omega$			12			
t _r	Turn-On Rise Time				11		ns	
$T_{D(off)}$	Turn-Off Delay Time				39			
t _f	Turn-Off Fall Time				18			
t _{rr}	Body Diode Reverse Recovery Time	I FOA d:/d+ 4004/			19		ns	
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =50A, di/dt =100A/μs			17		nC	

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

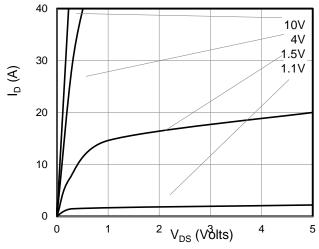


Figure 1: On-Region Characteristics

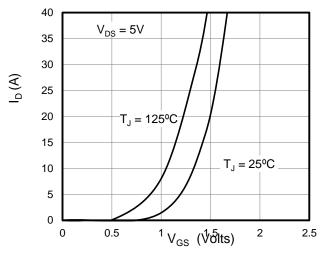


Figure 2: Transfer Characteristics

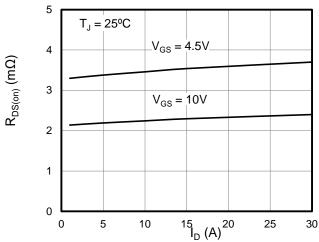


Figure 3: On-Resistance vs. Drain Current

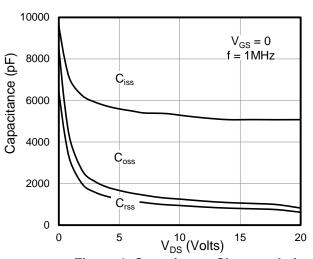


Figure 4: Capacitance Characteristics

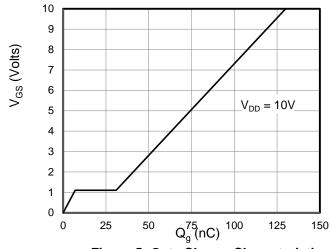


Figure 5: Gate Charge Characteristics

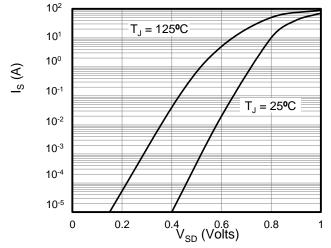


Figure 6: Body Diode Forward Voltage

 $Z_{\theta, JC}$ Normalized Transient Thermal Resistance

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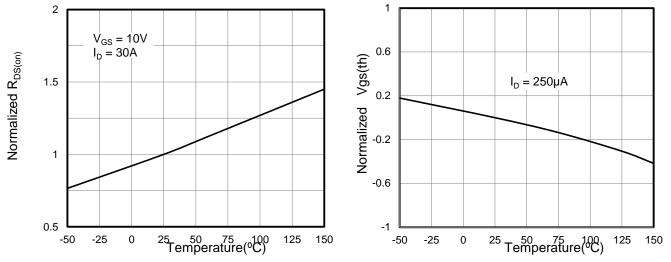


Figure 7: On-Resistance vs. Junction Temperature

Figure 8: Vgs(th) vs. Junction Temperature

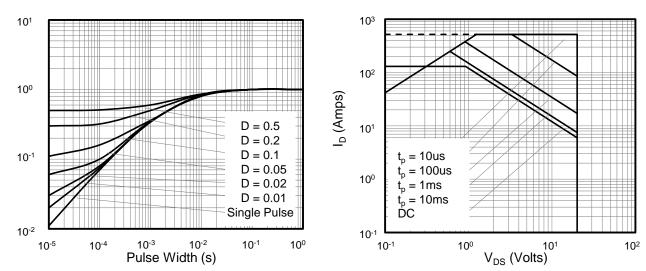


Figure 11: Normalized Transient Thermal Resistance

Figure 12: Safe Operating Area

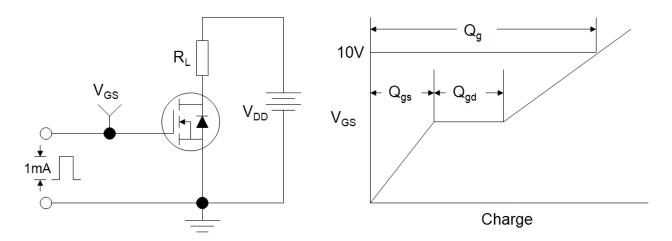


Figure A: Gate Charge Test Circuit and Waveforms

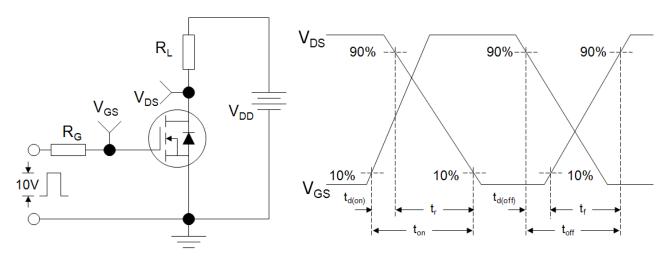


Figure B: Resistive Switching Test Circuit and Waveforms

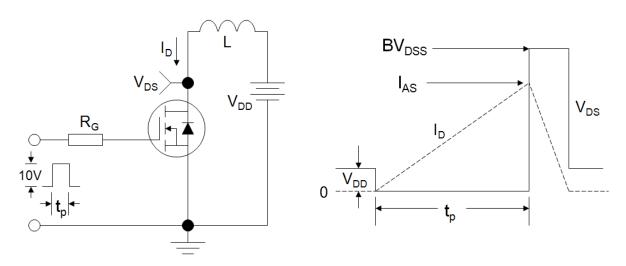
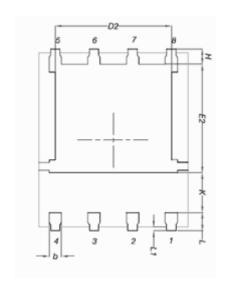
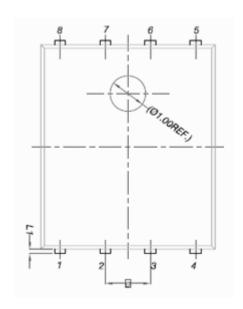


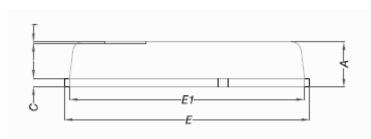
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms

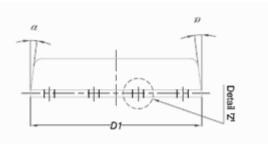


DFN5x6









DIM.	MILLIMETERS		544	MILLIMETERS			
	MIN.	NOM.	MAX.	DIM.	MIN.	NOM.	MAX.
Α	0.90	1.00	1.10	E	5.90	6.00	6.10
A1	0	-	0.05	E1	5.70	5.75	5.80
b	0.33	0.41	0.51	E2	3.38	3.58	3.78
С	0.20	0.25	0.30	е	1.27 BSC		
D1	4.80	4.90	5.00	Н	0.41	0.51	0.61
D2	3.61	3.81	3.96	K	1.10	-	-
				L	0.51	0.61	0.71
				L1	0.06	0.13	0.20
				α	O°	-	12°



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